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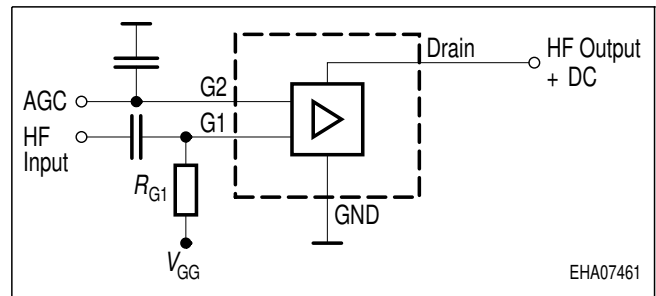
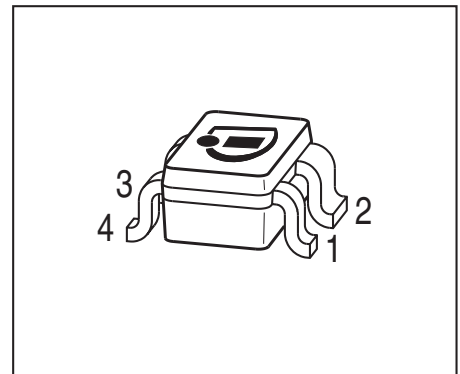
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Silicon N-Channel MOSFET Tetrode

- Low noise gain controlled input stages of UHF- and VHF - tuners with 3 V up to 5 V supply voltage
- Integrated gate protection diodes
- Excellent noise figure
- High gain, high forward transadmittance
- Improved cross modulation at gain reduction
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Pin Configuration						Marking
BF5020	SOT143	1 = S	2 = D	3 = G2	4 = G1	-	-	KYs
BF5020R	SOT143R	1 = D	2 = S	3 = G1	4 = G2	-	-	KYs
BF5020W	SOT343	1 = D	2 = S	3 = G1	4 = G2	-	-	KYs

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	8	V
Continuous drain current	I_D	25	mA
Gate 1/ gate 2-source current	I_{G1S}, I_{G2S}	± 10	mA
Gate 1/ gate 2-source voltage	V_{G1S}, V_{G2S}	± 6	V
Total power dissipation	P_{tot}		mW
$T_S \leq 76 \text{ }^\circ\text{C}$, BF5020, BF5020R		200	
$T_S \leq 94 \text{ }^\circ\text{C}$, BF5020W		200	
Storage temperature	T_{stg}	-55 ... 150	$^\circ\text{C}$
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point ¹⁾ BF5020, BF5020R BF5020W	R_{thchs}	≤ 370 ≤ 280	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

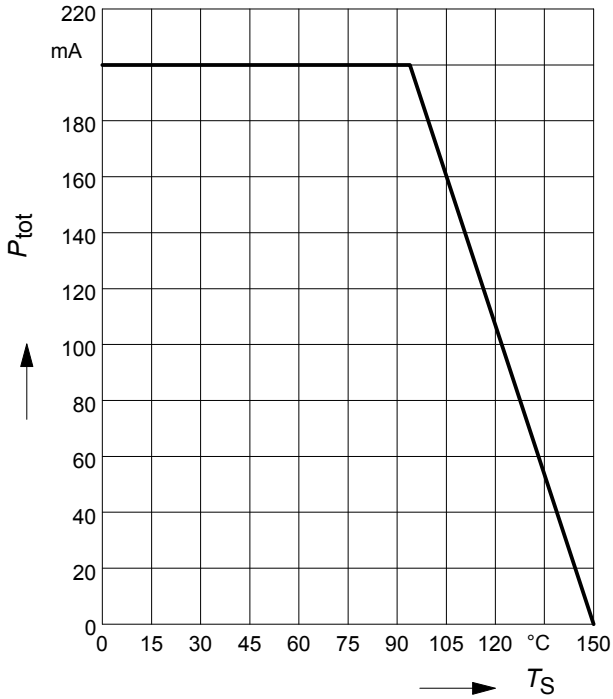
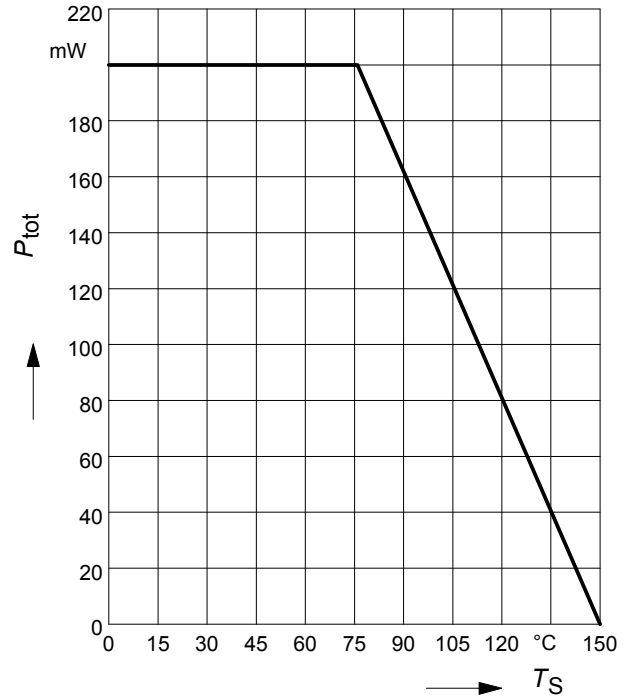
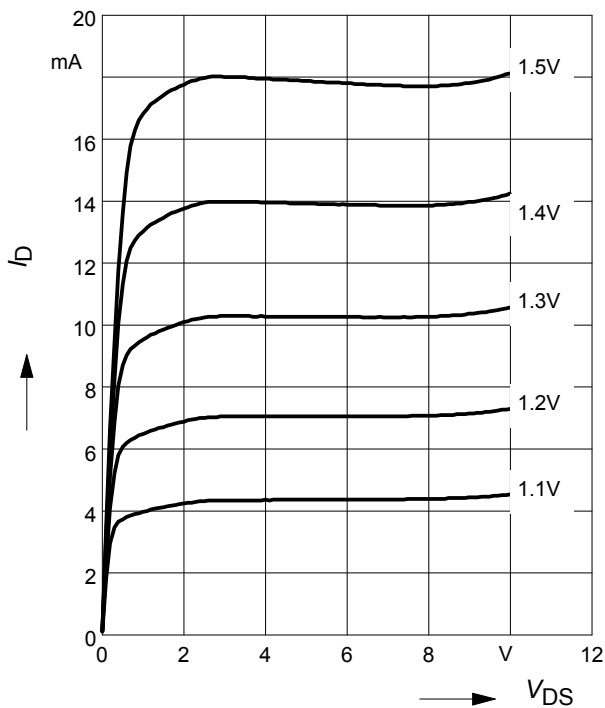
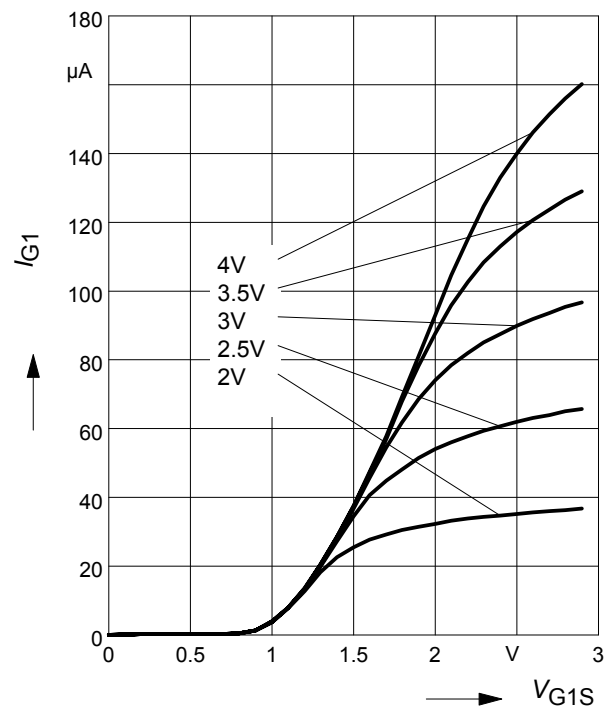
Drain-source breakdown voltage $I_D = 20 \mu\text{A}$, $V_{G1S} = 0$, $V_{G2S} = 0$	$V_{(BR)DS}$	12	-	-	V
Gate1-source breakdown voltage $+I_{G1S} = 10 \text{ mA}$, $V_{G2S} = 0$, $V_{DS} = 0$	$+V_{(BR)G1SS}$	6	-	15	
Gate2-source breakdown voltage $+I_{G2S} = 10 \text{ mA}$, $V_{G1S} = 0$, $V_{DS} = 0$	$+V_{(BR)G2SS}$	6	-	15	
Gate1-source leakage current $V_{G1S} = 6 \text{ V}$, $V_{G2S} = 0$, $V_{DS} = 0$	$+I_{G1SS}$	-	-	50	nA
Gate2-source leakage current $V_{G2S} = 6 \text{ V}$, $V_{G1S} = 0$, $V_{DS} = 0$	$+I_{G2SS}$	-	-	50	
Drain current $V_{DS} = 5 \text{ V}$, $V_{G1S} = 0$, $V_{G2S} = 4 \text{ V}$	I_{DSS}	-	-	100	
Drain-source current $V_{DS} = 5 \text{ V}$, $V_{G2S} = 4 \text{ V}$, $R_{G1} = 120 \text{ k}\Omega$	I_{DSX}	-	14	-	mA
Gate1-source pinch-off voltage $V_{DS} = 5 \text{ V}$, $V_{G2S} = 4 \text{ V}$, $I_D = 20 \mu\text{A}$	$V_{G1S(p)}$	-	0.7	-	V
Gate2-source pinch-off voltage $V_{DS} = 5 \text{ V}$, $I_D = 20 \mu\text{A}$, $V_{G1S} = 2 \text{ V}$	$V_{G2S(p)}$	-	0.7	-	

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

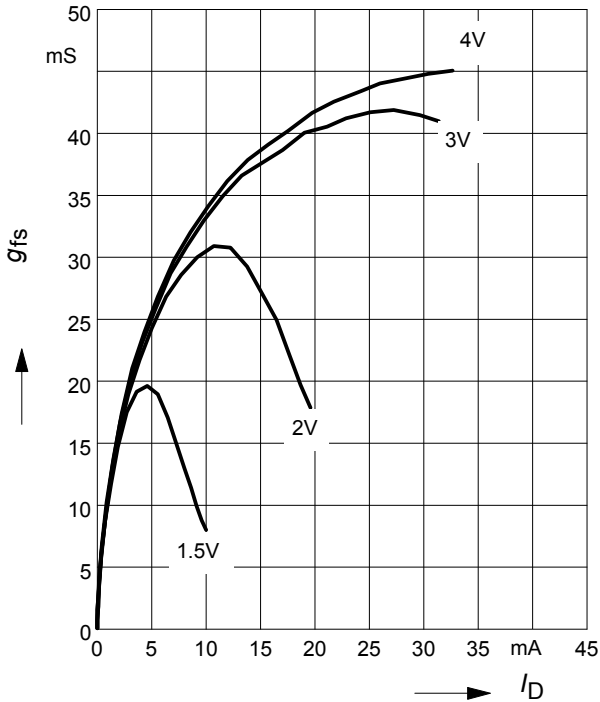
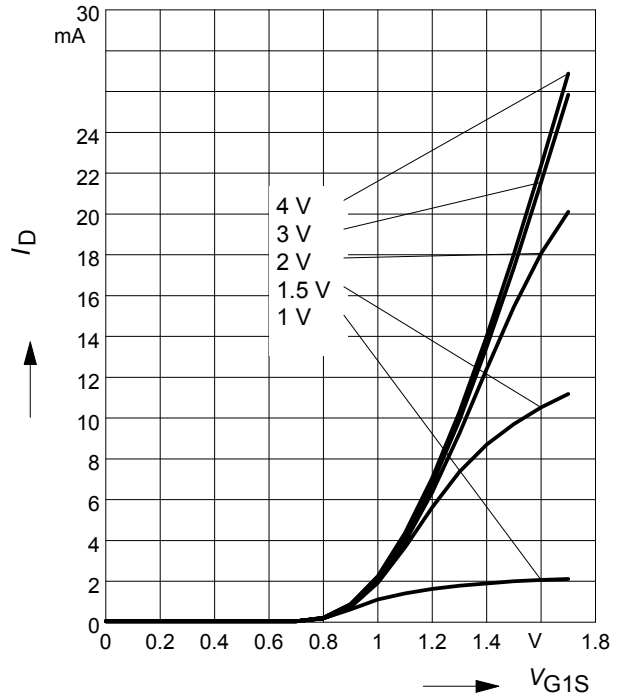
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics - (verified by random sampling)					
Forward transconductance $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$	g_{fs}	-	34	-	mS
Gate1 input capacitance $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$	C_{g1ss}	-	2.4	-	pF
Output capacitance $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$	C_{dss}	-	1	-	
Power gain $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$, $f = 800\text{ MHz}$ $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$, $f = 45\text{ MHz}$	G_p	-	26	-	dB
		-	32	-	
Noise figure $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$, $f = 800\text{ MHz}$ $V_{DS} = 5\text{ V}$, $I_D = 10\text{ mA}$, $V_{G2S} = 4\text{ V}$, $f = 45\text{ MHz}$	F	-	1.2	-	dB
		-	0.8	-	
Gain control range $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\dots 0\text{ V}$	ΔG_p	-	45	-	
Cross-modulation ¹⁾ , $V_{DS} = 5\text{ V}$, $R_{G1} = 120\text{ k}\Omega$ AGC = 0 AGC = 10 dB AGC = 40 dB	X_{mod}	-	98	-	dB μ V
		-	96	-	
		-	106	-	

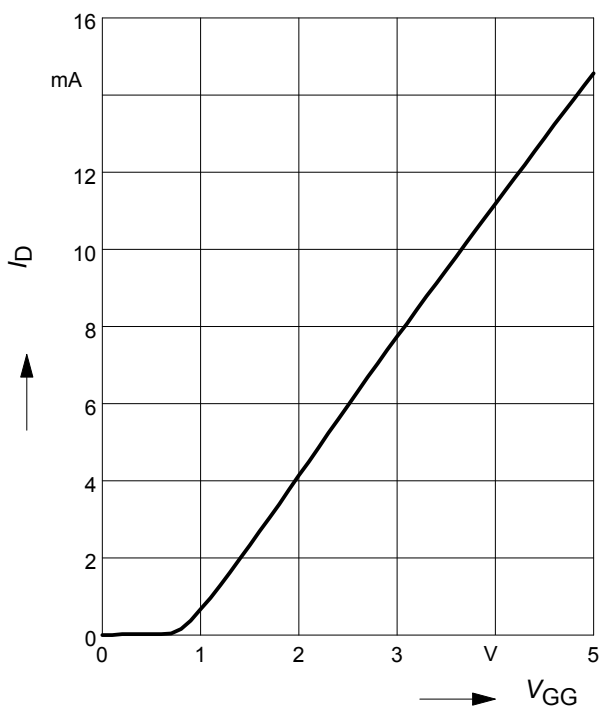
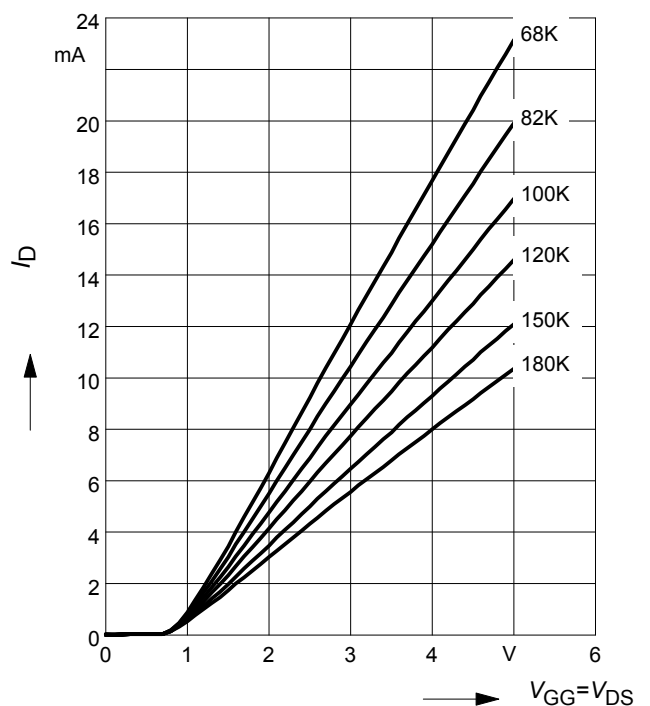
¹Input level for $k = 1\%$; $f_w = 50\text{ MHz}$, $f_{unw} = 60\text{ MHz}$

Total power dissipation $P_{tot} = f(T_S)$
BF5020W

Total power dissipation $P_{tot} = f(T_S)$
BF5020, BF5020R

Output characteristics $I_D = f(V_{DS})$

Gate 1 current $I_{G1} = f(V_{G1S})$
 $V_{DS} = 5V$
 $V_{G2S} = \text{Parameter}$


Gate 1 forward transconductance

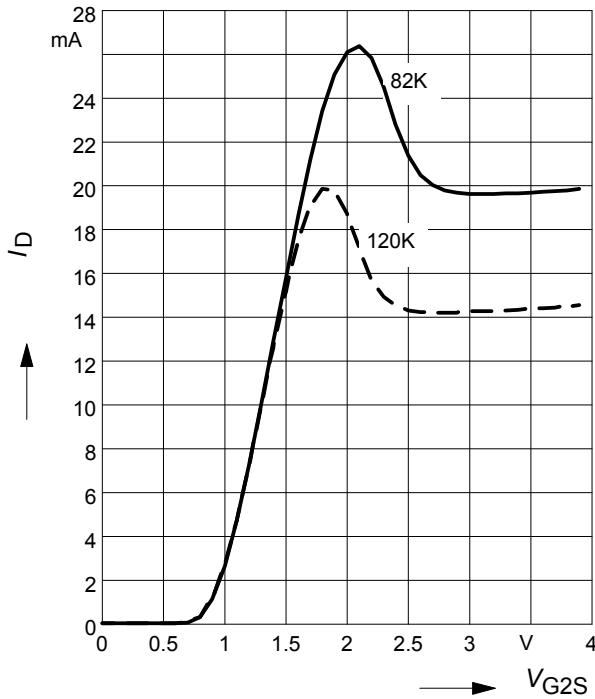
$$g_{fs} = f(I_D)$$

 $V_{DS} = 5V, V_{G2S} = \text{Parameter}$

Drain current $I_D = f(V_{G1S})$
 $V_{DS} = 5V$
 $V_{G2S} = \text{Parameter}$

Drain current $I_D = f(V_{GG})$
 $V_{DS} = 5V, V_{G2S} = 4V, R_{G1} = 120 \text{ k}\Omega$

 (connected to V_{GG} , $V_{GG} = \text{gate1}$ supply voltage)

Drain current $I_D = f(V_{GG})$
 $V_{G2S} = 4V$
 $R_{G1} = \text{Parameter in k}\Omega$


Drain current $I_D = f(V_{G2S})$

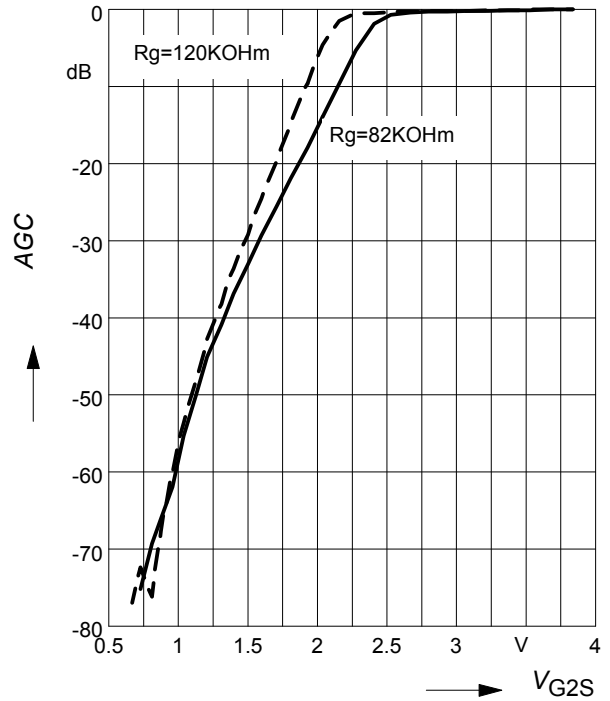
$V_{DS} = 5\text{ V}$, $R_{G1} = \text{Parameter in k}\Omega$



AGC characteristic $AGC = f(V_{G2S})$

$f = 50\text{ MHz}$

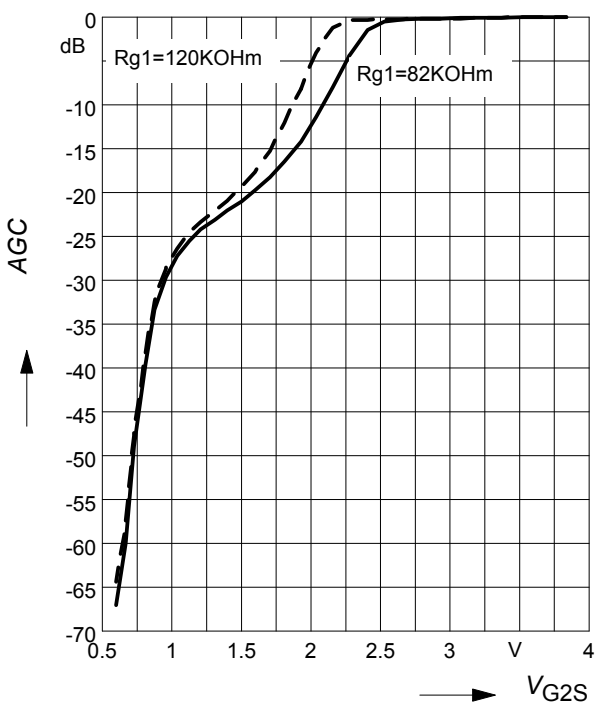
measured in test circuit, see page 7



AGC characteristic $AGC = f(V_{G2S})$

$f = 800\text{ MHz}$

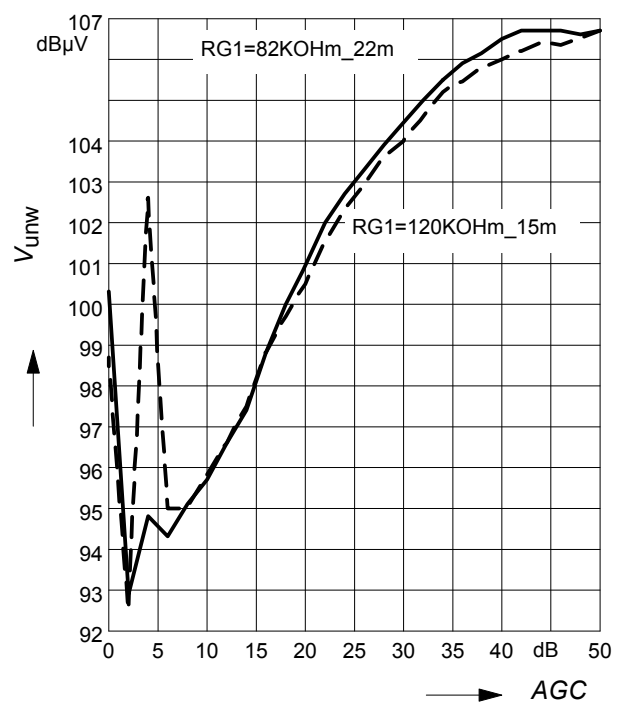
measured in test circuit, see page 7



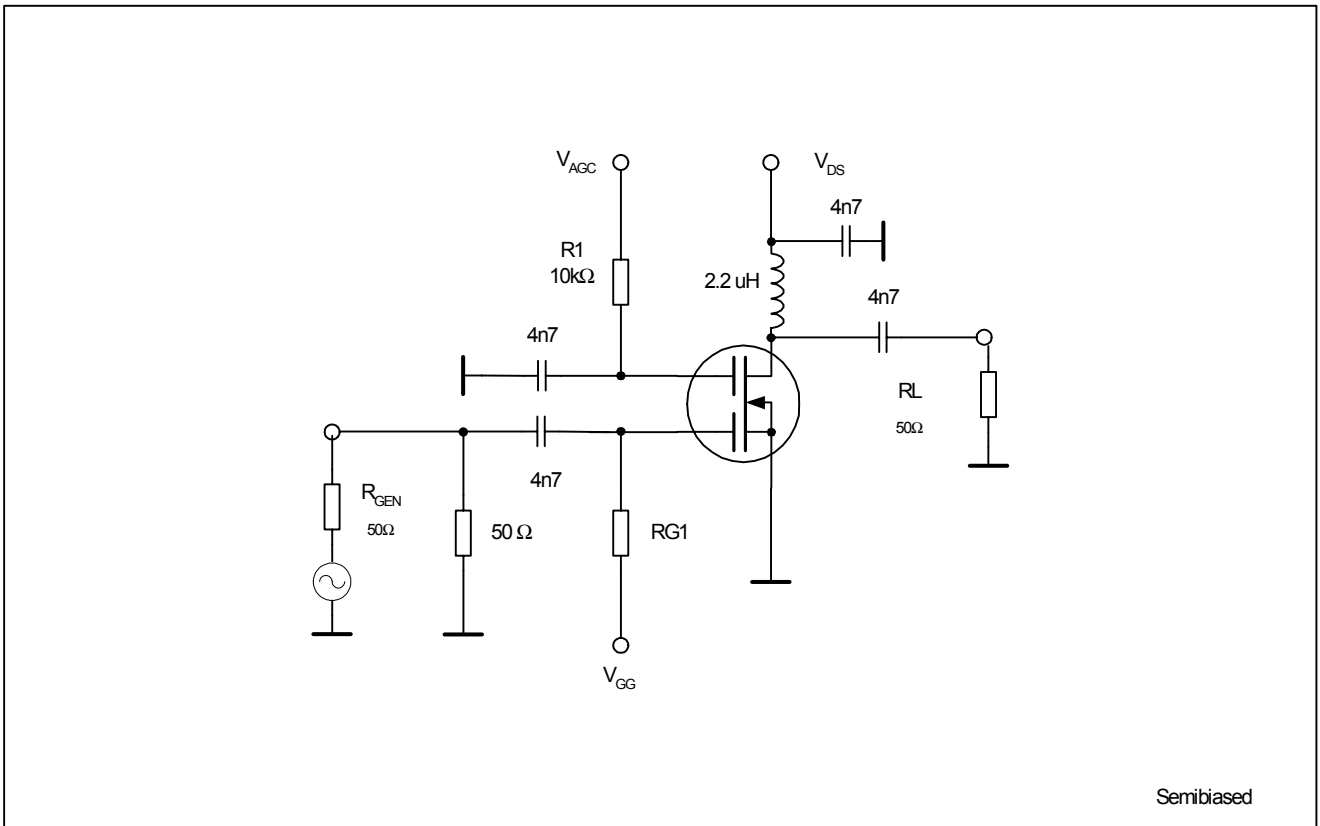
Crossmodulation $V_{unw} = (AGC)$

$V_{DS} = 5\text{ V}$

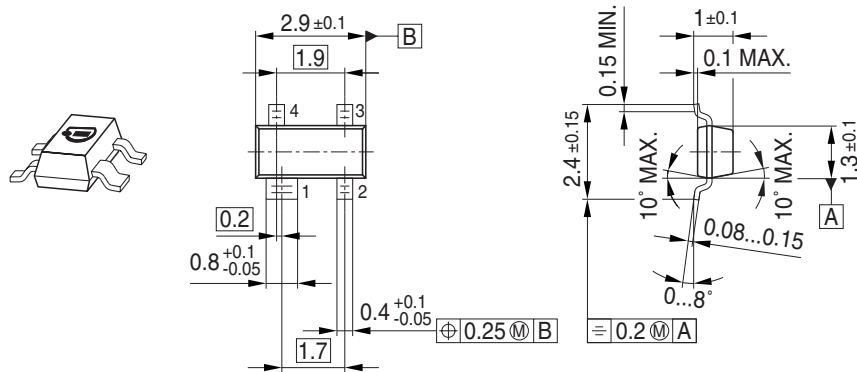
measured in test circuit, see page 7



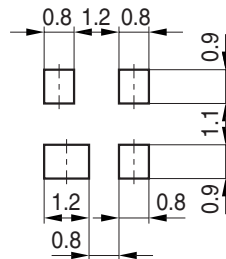
Test circuit for Crossmodulation / AGC



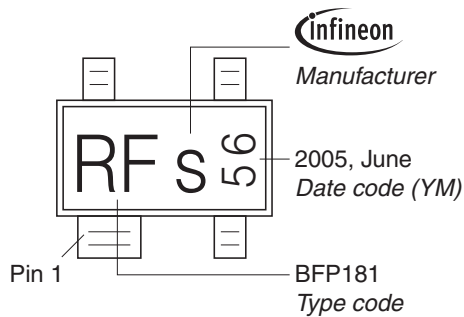
Package Outline



Foot Print

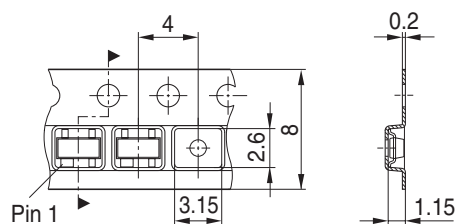


Marking Layout (Example)

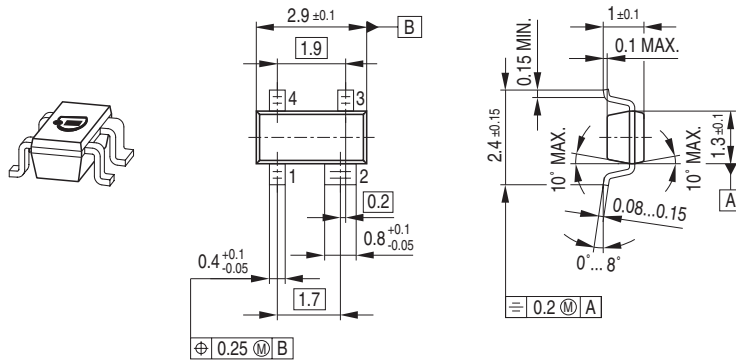


Standard Packing

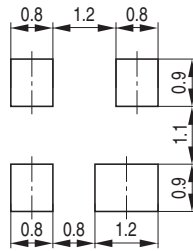
Reel $\phi 180$ mm = 3.000 Pieces/Reel
 Reel $\phi 330$ mm = 10.000 Pieces/Reel



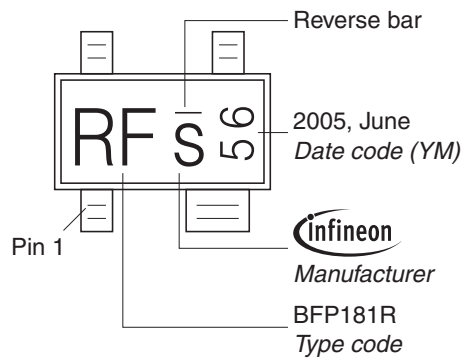
Package Outline



Foot Print

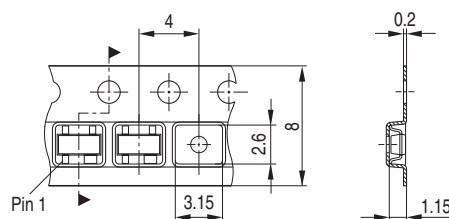


Marking Layout (Example)

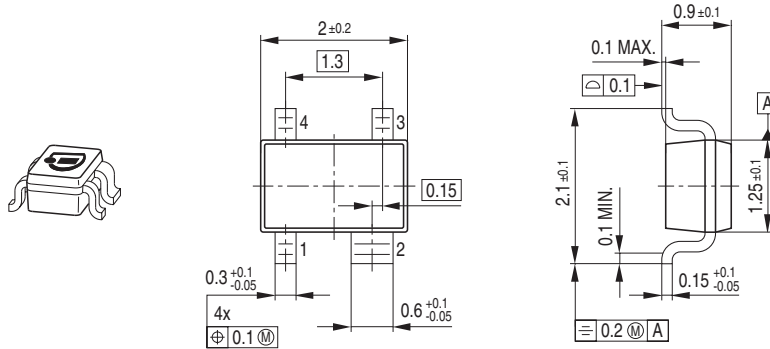


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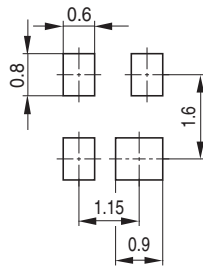
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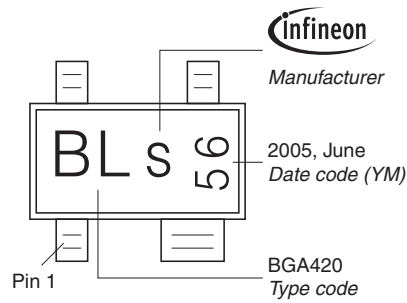
Package Outline



Foot Print

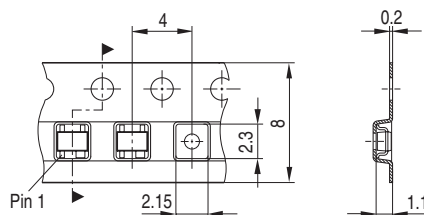


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



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